Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model
[List multiple models if applicable.]
HP ProBook 4440s/4441s Notebook PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Mother Board</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Main battery, RTC battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries No</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps Panel</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Yes, AC power cord</td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations. No</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td>No</td>
<td>0</td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)
Components, parts and materials containing refractory ceramic fibers | No | 0
Components, parts and materials containing radioactive substances | No | 0

2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 Cross screwdriver</td>
<td>#1</td>
</tr>
<tr>
<td>Description #2 Nipper</td>
<td>#1</td>
</tr>
<tr>
<td>Description #3 T8 screwdriver</td>
<td>#1</td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Take off the battery package from system bottom side.
2. Take off access door from system bottom side.
3. Loose HDD module screws and take off HDD module from system.
4. Loose ODD module screws and take off ODD module from system.
5. Loose thermal bracket screw and take off thermal bracket.
6. Loose Fan screws and take off fan.
7. Loose l-case to u-case screws and KB module screw.
8. Loose u-case to l-case screws and take off KB module.
9. Take off u-case sub-assembly.
10. Loose speaker screw and take off speaker.
11. Loose MB screws and take off DC-IN cable from MB.
12. Loose hinge screws and take off hinge-up assembly.
13. Loose bezel screw and take off bezel sub-assembly.
14. Loose screws from hinge and take off LCD hinge.
15. Loose screws from LCD module and take off LCD module from panel cover.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Disassembly process:

1. Take off Battery
2. Remove Access Door
3. Loose the HDD bracket screw first, and take off HDD
4. Loose Thermal bracket screws, and take off bracket.
5. Remove ODD screw, Take off ODD module.

Components:
- Battery
- HDD
- Thermal bracket
- ODD
- Screw
1. Loose the Fan screws and take off Fan
2. Loose u-case screws, De-assembly cable routing.
1. Move down keyboard module and take off Keyboard.
2. Loose u-case screws and two FFC cable.
3. Take off U-case.
1. Loose speaker screws and take off speaker.
2. Loose the battery cable and take off cable.
3. Loose the M/B screws and take off M/B.
1. Loose K-lock screws and take off K-Lock.
2. Take off hinge cap
3. Loose screw

1 Speaker
2 Hinge CAP
3 Screw

Roadrunner (Intel)
1. Loose LCD screws
2. Take off LCD

Bezel

Screw